TELEFUNKEN Semiconductors

Optocoupler with Phototransistor Output

Description

The 4N35/ 36/ 37 consist of a phototransistor optically coupled to a gallium arsenide infrared emitting diode in a 6 lead plastic dual inline packages.

The elements are mounted on one leadframe in coplanar technique, providing a fixed distance between input and output for highest safety requirements.

Applications

Galvanically separated circuits, for general purposes.



Features

- Isolation test voltage (RMS) 3.75 kV
- UL recognized, file No. E-76222

- Low coupling capacity typical 0.3 pF
- Current Transfer Ratio > 100%
- Low temperature coefficient of the CTR

Order Schematic

Part Numbers	CTR-Ranking
4N35/4N35S	> 100%
4N36/ 4N36S	> 100%
4N37/4N37S	> 100%

Suffix: S = Waterproofed device

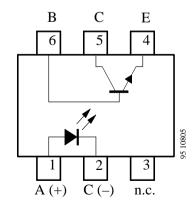
Remarks

For those couplers, where instead of standard soldering/cleaning process a pure water cleaning process is being used, we suggest our waterproofed construction. In this case please order the part numbers with the suffix "S". The waterproofed construction, corresponding with the coupling system "S", and does not belong to the part number itself.

Standard parts are marked with the letter "A".

This coupling system indicator "A" or "S" is in a separate (second) line of the marking.

Pin Connection





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Absolute Maximum Ratings

Input (Emitter)

Parameters	Test Conditions	Symbol	Value	Unit
Reserve voltage		V_{R}	6	V
Forward current		I_{F}	60	mA
Forward surge current	$t_p \le 10 \ \mu s$	I_{FSM}	3	A
Power dissipation	$T_{amb} \le 25^{\circ}C$	P_{V}	100	mW
Junction temperature		T _i	125	°C

Output (Detector)

Parameters	Test Conditions	Symbol	Value	Unit
Collector base voltage		V_{CBO}	70	V
Collector emitter voltage		V_{CEO}	30	V
Emitter collector voltage		V _{ECO}	7	V
Collector current		$I_{\mathbf{C}}$	50	mA
Peak collector current	$t_p/T = 0.5, t_p \le 10 \text{ ms}$	I _{CM}	100	mA
Power dissipation	$T_{amb} \le 25^{\circ}C$	P _V	150	mW
Junction temperature		Ti	125	°C

Coupler

Parameters	Test Conditions	Symbol	Value	Unit
Isolation test voltage (RMS)		V _{IO} 1)	3.75	kV
Total power dissipation	$T_{amb} \le 25^{\circ}C$	P _{tot}	250	mW
Ambient temperature range		T _{amb}	-55 to +100	°C
Storage temperature range		T _{stg}	-55 to +125	°C
Soldering temperature	2 mm from case, $t \le 10 \text{ s}$	T_{sd}	260	°C

¹⁾ related to standard climate 23/50 DIN 50014

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Electrical Characteristics

 $T_{amb} = 25$ °C, unless otherwise specified

Input (Emitter)

Parameters	Test Conditions	Symbol	Min.	Тур.	Max.	Unit
Forward voltage	$I_F = 10 \text{ mA}$	V_{F}		1.2	1.5	V
_	$T_{amb} = 100$ °C	$V_{ m F}$			1.4	V
Breakdown voltage	$I_R = 10 \mu A$	V _(BR)	6			V
Junction capacitance	$V_R = 0$, $f = 1$ MHz	Ci		50		pF

Output (Detector)

Parameters	Test Conditions	Symbol	Min.	Тур.	Max.	Unit
Collector base breakdown voltage	$I_C = 100 \mu\text{A}$	V _{(BR)CBO}	70			V
Collector emitter breakdown voltage	$I_C = 1 \text{ mA}$	V _{(BR)CEO}	30			V
Emitter collector breakdown voltage	$I_E = 100 \ \mu A$	V _{(BR)ECO}	7			V
Collector dark current	$I_{F} = 0, E = 0 \\ V_{CE} = 10 \text{ V}, \\ V_{CE} = 30 \text{ V}, \\ T_{amb} = 100^{\circ}\text{C}$	I _{CEO}		5	50 500	nA μA

Coupler

Parameters	Test Conditions	Symbol	Min.	Тур.	Max.	Unit
Isolation test voltage (RMS)	f = 50 Hz, t = 2 s	V _{IO} 1)	3.75			kV
Isolation resistance	V _{I0} = 1 kV, 40% relative humidity	R _{IO} 1)		10^{12}		Ω
I_{C}/I_{F}	$I_F = 10 \text{ mA}, V_{CE} = 10 \text{ V}$ $T_{amb} = 100 \text{°C}$	CTR CTR	1 0.4			
Collector emitter saturation voltage	$I_F = 10 \text{ mA},$ $I_C = 0.5 \text{ mA}$	V _{CEsat}			0.3	V
Cut-off frequency	$\begin{split} I_F &= 10 \text{ mA}, \text{ V}_{CE} = 5 \text{ V}, \\ R_L &= 100 \Omega \end{split}$	f_c		110		kHz
Coupling capacitance	f = 1 MHz	C_k		0.3		pF

¹⁾ related to standard climate 23/50 DIN 50014

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Switching Characteristics

 $V_S = 10 \text{ V}, I_C = 2 \text{ mA}, R_L = 100 \Omega$, see figure 1

Parameters	Test Conditions	Symbol	Min.	Тур.	Max.	Unit
Turn-on time		t _{on}		5.5	10	μs
Turn off time		t _{off}		4.5	10	μs

 $V_S = 5 \text{ V}, I_F = 10 \text{ mA}, R_L = 1 \text{ k}\Omega, \text{ see figure } 2$

Parameters	Test Conditions	Symbol	Min.	Тур.	Max.	Unit
Turn-on time		t _{on}		9		μs
Turn-off time		t _{off}		18		μs

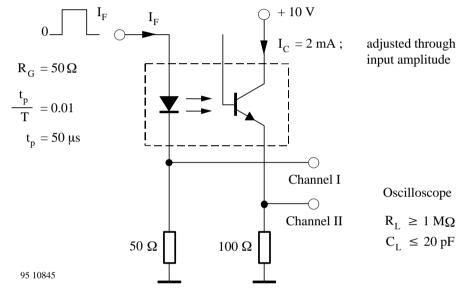


Figure 1. Test circuit, non-saturated operation

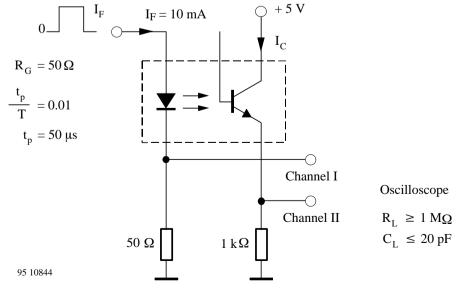
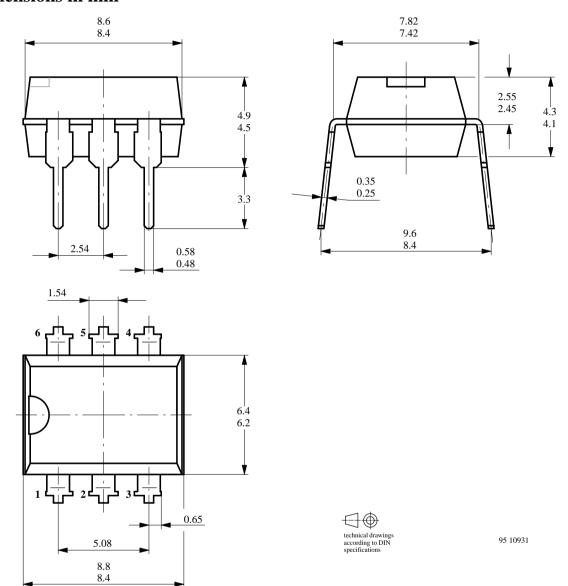


Figure 2. Test circuit, saturated operation

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Dimensions in mm



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4N35/4N36/4N37

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Ozone Depleting Substances Policy Statement

It is the policy of TEMIC TELEFUNKEN microelectronic GmbH to

- 1. Meet all present and future national and international statutory requirements.
- 2. Regularly and continuously improve the performance of our products, processes, distribution and operating systems with respect to their impact on the health and safety of our employees and the public, as well as their impact on the environment.

It is particular concern to control or eliminate releases of those substances into the atmosphere which are known as ozone depleting substances (ODSs).

The Montreal Protocol (1987) and its London Amendments (1990) intend to severely restrict the use of ODSs and forbid their use within the next ten years. Various national and international initiatives are pressing for an earlier ban on these substances.

TEMIC TELEFUNKEN microelectronic GmbH semiconductor division has been able to use its policy of continuous improvements to eliminate the use of ODSs listed in the following documents.

- 1. Annex A, B and list of transitional substances of the Montreal Protocol and the London Amendments respectively
- 2. Class I and II ozone depleting substances in the Clean Air Act Amendments of 1990 by the Environmental Protection Agency (EPA) in the USA
- 3. Council Decision 88/540/EEC and 91/690/EEC Annex A, B and C (transitional substances) respectively.

TEMIC can certify that our semiconductors are not manufactured with ozone depleting substances and do not contain such substances.

We reserve the right to make changes to improve technical design and may do so without further notice. Parameters can vary in different applications. All operating parameters must be validated for each customer application by the customer. Should the buyer use TEMIC products for any unintended or unauthorized application, the buyer shall indemnify TEMIC against all claims, costs, damages, and expenses, arising out of, directly or indirectly, any claim of personal damage, injury or death associated with such unintended or unauthorized use.

TEMIC TELEFUNKEN microelectronic GmbH, P.O.B. 3535, D-74025 Heilbronn, Germany Telephone: 49 (0)7131 67 2831, Fax number: 49 (0)7131 67 2423

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